



## Features 特性

- Thermal Conductivity  
导热系数 12.0 W/m·K
- Natural Tackiness 自黏性
- Low Compress Stress  
低压缩应力
- Low Thermal Resistance  
低热阻

## Applications 产品应用

- Consumer Electronics  
消费电子
- Network Equipment  
网通设备
- Voltage Regulation Modules  
电压调节模块
- High Speed Storage Drive  
高速存储驱动器

**Thermal GP1200** 导热硅胶垫片是一款高导热性能的材料，双面微粘装配使用时，能够发热器件在散热片或金属底座之间构建良好的导热通路，低压缩力下表现出较低的热阻和较好的电气绝缘特性。

**Thermal GP1200** thermal conductive silicone gap pad is a kind of material with high thermal conductivity. Owing to double-sided natural tackiness, the material can build up a good heat conduction path between the heat sink and the metal substrate during assembly. The product shows low thermal resistance and good electrical insulation properties under low compression force.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体		—
Color 颜色	Gray 灰色	—	Visual 目视
Thermal Conductivity 导热系数	12.0	W/m·K	ASTM D5470
Thickness 厚度	0.5 - 5.0	mm	ASTM D374
Hardness 硬度 (Shore 00)	60 - 85	—	ASTM D2240
Oil Bleeding 渗油率	0.5	%	125°C 48H 50% 压缩
Density 密度	3.3	g/cm <sup>3</sup>	ASTM D792
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	8.0	KV/mm	ASTM D149
Volume Resistivity 体积电阻率	10 <sup>13</sup>	Ω.cm	ASTM D257
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	12	month	25±5°C, 50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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